**256 Ball Fine-Pitch Thin BGA (FT256/FTG256) Package**

**BOTTOM VIEW**

**TOP VIEW**

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**FTE56 - 63/37 (Sn/Pb) SOLDER BALLS**
**FTGE56 - Sn/Ag/Cu SOLDER BALLS**

**NOTES:**

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034 AAF-1 EXCEPT FOR THE SOLDER BALL SIZE.
Revision History

The following table shows the revision history for this document.

<table>
<thead>
<tr>
<th>Date</th>
<th>Version</th>
<th>Description of Revisions</th>
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<tr>
<td>03/23/05</td>
<td>1.2.1</td>
<td>Update.</td>
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<tr>
<td>10/05/07</td>
<td>1.3</td>
<td>Changed the A1 minimum dimension to 0.30 mm.</td>
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<tr>
<td>03/23/11</td>
<td>1.4</td>
<td>Changed the FTG256 solder ball description.</td>
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